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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: DUAL FLAT NO LEAD
COL PACKAGE (DFN-COL)
10 TERMINAL, 0.5 PITCH (3 X 3 X 0.9)

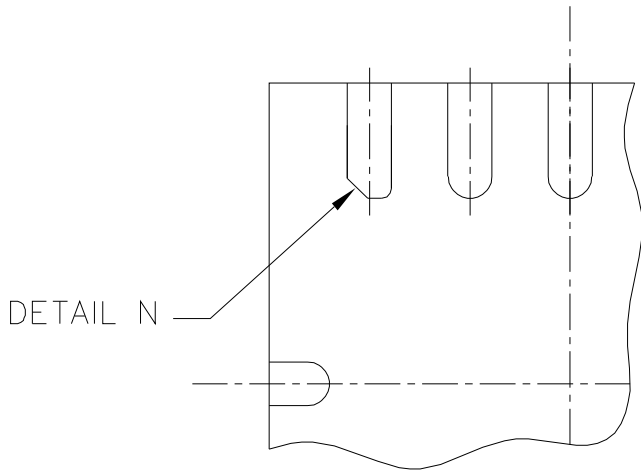
DOCUMENT NO: 98ASA10816D

REV: B

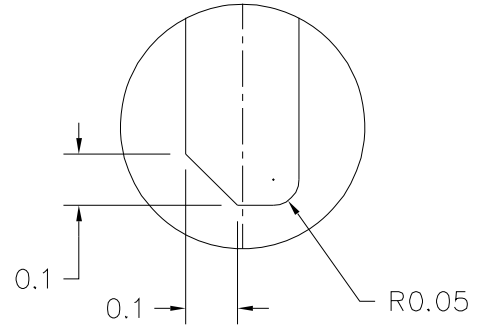
CASE NUMBER: 2002-03

14 AUG 2008

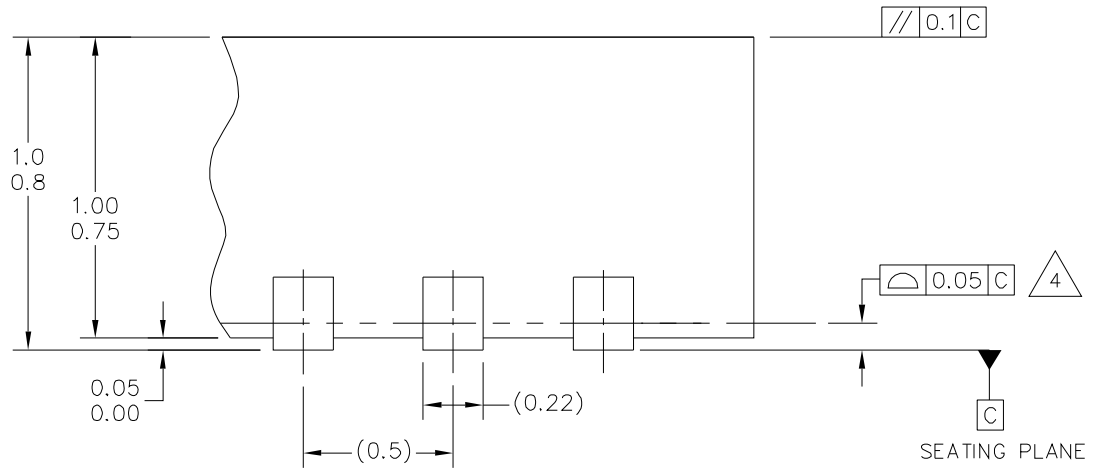
STANDARD: NON JEDEC



DETAIL M
PIN 1 BACKSIDE INDEX




DETAIL N
PIN 1 BACKSIDE INDEX



DETAIL G

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. THIS IS NON JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND ALL OTHR BOTTOM SURFACE METALLIZATION.
5. MIN. METAL GAP SHOULD BE 0.2MM.

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